

### SSM Institute of Engineering and Technology, Dindigul-02.

### **Department of Electrical and Electronics Engineering**

### **CIRCULAR**

03.10.2019

This is to inform that value added program on PCB Design and Fabrication is going to be conducted for IV year EEE students from 02.12.2019 to 07.12.2019 by Er.S.P.Sarathy Retired Employee from Schneider Electric System India Pvt. Ltd, Chennai. Henceforth interested students are informed to register their name to Mr.G.Satheesh Kumar, AP/EE on or before 24.10.2019.

Faculty Incharge

HoD/EEE

### PCB DESIGN AND FABRICATION

### Syllabus

### Module I: (9 Hrs)

Introduction to Printed circuit board: fundamental of electronic components, basic electronic circuits, Basics of printed circuit board designing: Layout planning, general rules and parameters, ground conductor considerations, thermal issues, check and inspection of artwork.

### Module II: (6 hrs)

Design rules for PCB: Design rules for Digital circuit PCBs, Analog circuit PCBs, high frequency and fast pulse applications, Power electronic applications, Microwave applications

### Module III: (10 hrs)

Footprints, Assigning Footprint to components, Net listing, PCB Layout Designing, Auto routing and manual routing. Assigning specific text (silkscreen) to design, Creating report of design, creating manufacturing data (GERBER) for design.

### Module IV: (7 hrs)

Introduction printed circuit board production techniques: Photo printing, film- master production, reprographic camera, basic process for double sided PCBs photo resists, Screen printing process, plating, relative performance and quality control, Etching machines, Solders alloys, fluxes, soldering techniques, Mechanical operations.

### Module V: (6 hrs)

PCB Technology Trends: Multilayer PCBs. Multiwire PCB, Flexible PCBs, Surface mount PCBs, Reflow sudering, Introduction to High-Density Interconnection (HDI) Technology.

### Module VI: (7 hrs)

PCB design for EMI/EMC: Subsystem/PCB Placement in an enclosure, Filtering circuit placement, decoupling and bypassing, Electronic discharge protection, Electronic waste; Printed circuit boards Recycling techniques, Introduction to Integrated Circuit Packaging and footprints, NEMA and IPC standards.

### Text Books:

1. Printed circuit board design, fabrication assembly and testing By R. S. Khandpur, Tata McGraw Hill 2006

### Reference Books:

- 1. Printed circuit Board Design and technology, Walter C. Bosshart
- 2. Printed Circuits Handbook, Sixth Edition, by Clyde F. Coombs, Jr, Happy T.Holden, Publisher: McGraw-Hill Education Year: 2016



### SSM Institute of Engineering and Technology Sindalagundu post, Palani main road, Dindigul – 624002, Tamilnadu.

DEPARTMENT OF ELECTRICAL AND ELECTRONICS ENGINEERING IV YEAR NAME LIST (2019-2020)

11	IV YEAR NAM!	E LIST (2019-2020)
S.NO	REGISTER NO	
1	922116105001	ABIRAMI R
2	922116105002	ANITHA K
3	922116105003	AZEEMA M
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5	922116105005	BANUPRIYA N
6	922116105006	DEVA SALOMI PRIYAM R
7	922116105007	DHAMOTHARAN R
8	922116105008	DHARANI N
9	922116105009	GOKUL P
10	922116105010	GOPI V
11	922116105011	HUDSON SAMRAJ A
12	922116105012	JAYAKKRISHNAN S
13	922116105013	JEYASHREE P
14	922116105014	KALAISELVAN N
15	922116105015	KANNAN P
16	922116105016	KANNI PRAKASH D
17	922116105017	KARTHICK A
18	922116105018	MALATHI S
19	922116105019	MATHUMITHA B
20	922116105020	MOHAN RAJ S
21	922116105021	MYTHELI S
22	922116105022	PREETHI R
23	922116105023	PRIYADHARSHINI J
24	922116105024	RAMANI CHIARA D
25	922116105025	RANJITH BABU S
26	922116105026	RESHMA S K
27	922116105027	RISHYA DORA S
28	922116105028	SARAVANAN A
		SIMRIN BANU A
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31	922116105032	SUBA LAKSHMI S
32	922116105033	SURIYA C R
33	922116105034	SURYA S R
34	922116105035	VIJAYALAKSHMI M C S
35	922116105036	VISHNU KUMAR S
36	922116105037	YOGA JOTHI C
37	922116105303	S.RUBAN RAJ
38	922116105303	M.SATHEESH KUMAR
38	922116105304	
40	922116105701	S.VASIM AKRAM

Class Incharge

HoD/EEE



Dindigul – Palani Highway, Dindigul – 624 002

Department of Electrical and Electronics Engineering

Hands on Training in PCB Design and Manufacturing

### STUDENT FEEDBACK FORM

year/Sem:		
Date:		
Dear Student,		

Thank you for your participation Hands on Training in **PCB Design and Fabrication**. We would like to hear from you - areas that you find useful and areas that you think we can do better. Your feedback will help us evaluate the effectiveness of this program and allow us to make improvements in future.

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S.No	Criteria	Excellent	Very good	Good	Fair	Satisfactory
1	Course content				5.0	0
2	Skill development					
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8	Outcome				54	

Feel free to give QUALITATIVE comments too

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Dindigul – Palani Highway, Dindigul – 624 002

Department of Electrical and Electronics Engineering

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Feel free to give QUALITATIVE comments too

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Year/Sem:

Date:

### SSM INSTITUTE OF ENGINEERING AND TECHNOLOGY

Dindigul – Palani Highway, Dindigul – 624 002

Department of Electrical and Electronics Engineering

Hands on Training in PCB Design and Manufacturing

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Dear Student,					.48	
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Feel free to give QUALITATIVE comments too

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Dindigul – Palani Highway, Dindigul – 624 002

### Department of Electrical and Electronics Engineering

### Value added course on PCB Design and Manufacturing

### STUDENT FEEDBACK FORM

Year/Sem:			
Date:			

Dear Student,

Thank you for your participation Value added Course on **PCB Design and Fabrication**. We would like to hear from you - areas that you find useful and areas that you think we can do better. Your feedback will help us evaluate the effectiveness of this program and allow us to make improvements in future.

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Feel free to give QUALITATIVE comments too

Signature of the student with name

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Year/Sem:

Date:

Dindigul – Palani Highway, Dindigul – 624 002

### Department of Electrical and Electronics Engineering

Value added course on PCB Design and Manufacturing

### STUDENT FEEDBACK FORM

Dear Student,	
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7	Individual attention					
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Feel free to give QUALITATIVE comments too

Signature of the student with name



## SSM INSTITUTE OF ENGINEERING AND TECHNOLOGY Dindigul – Palani Highway, Dindigul – 624 002 DEPARTMENT OF ELECTRICAL AND ELECTRONICS ENGINEERING

Value added Course on PCB Design & Fabrication Students Attendance Report

Roll No.	Register No.	Name of the Student	03.12	. 20 (8	04.12.2018	2018	05.1	05.12.2018	8100:01.90	81000	67.12.2018	20/8	08.12.2018	2018
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Max. Marks: 20 Marks

### SSM INSTITUTE OF ENGINEERING AND TECHNOLOGY

Dindigul – Palani Highway, Dindigul – 624 002

Department of Electrical and Electronics Engineering Value added Course on PCB Fabrication and Manufacturing

### Assessment Question

Answer for all the question	(Each qu	uestions carry	one mark)
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1. Which phenomenon is not reduced by the circuit paths of lowest impedances especially provided by power and return planes for shielding purposes?

- a) Radiation
- b) Convection

Noise

d) Crosstalk

2. High current	circuits are pur	posely located	or placed	near the	edge of PCB	in accordance	to the supply
ines for 🛚							

- a) Removal of heat
- b) Isolation of stray current
- c) Reduction of path length
- d) All of the above
- 3. Which among the below stated soldering methods is also renowned as 'High Frequency Resistance Soldering'?
- a) Iron Soldering
- b) Furnace Soldering
- Torch Soldering
- d) Electrical Soldering
- 4. Which among the below mentioned approaches belongs to the category of In-circuit Testing?
- a) Impedance Testing
- b) Component Testing
- c) Apply Signal and check output
- d) All of the above
- 5. Which type of solderability testing is carried out for the generation of solder sample due to immersion of wire or sheet metal specimen in a bath of molten solder?
- a) Solder Bath Testing
- b) Meniscus Rise Testing
- c) Solder Iron Testing
- d) None of the above

- 6. What is/are the necessity/ies to provide guarding to precision differential amplifiers?
- a) To increase leakage resistance
- b) To reduce capacitance between signal conductors & ground
- c) Both a and b
- d) None of the above
- 7. Which among the below mentioned assertions is not a way of cross-talk reduction while designing digital PCBs?
- a) Decrease in the distance between conductors
- b) Shielding of clock lines with guard strips
- c) Reduction in the loop area of circuits
- d) Avoid running of parallel traces for longer distances especially for asynchronous signals
- 8. Which among the below mentioned packages does not belong to the category of 'Small Outline Packages'
- a) SO
- b) SOP
- c) SOT
- d) SON
- 9. Which among the below specified assertions is not a grounding consideration associated with ADC as well as DAC?
- a) Analog side to analog ground
- b) Digital side to digital ground
- c) Use of separate power supply and connection of their ground leads to single point reference
- d) Reduction of inductive loop area between power and return traces
- 10. Which among the below stated devices/equipments are preferred for elimination of ground and suppline noise especially in TTL/CMOS / ECL PCB designing?
- a) Coupling capacitor
- b) Decoupling capacitor
- c) Snubber circuits
- d) All of the above
- 11. Which among the below specified condition is precise in the crosstalk verification mechanism using logic flow in opposite direction with the limit of avoiding dangerous interference in digital PCB designing?
- a)  $Z_{even} > Z_{odd}$
- b)  $Z_{odd} \ge 0.5 Z_{even}$
- c)  $Z_{odd} \ge 0.8 Z_{even}$
- d)  $Z_{odd} = Z_{even}$

d) Solder mask
13. Which problems are about to occur if PCB is not designed properly in a confined manner for digital
circuits?
A. Diffraction
B. Refraction
C. Ground & Supply-line Noise
D. Electromagnetic Interference
A & B
b) B & C
c) C & D
d) A, B, C, D
14 37/11 1 1 1 4 6 11 1 1 1 1 1 1 1 1 1 1 1 1
14. Which among the following assists in obtaining the desired value of wave impedance in reflection phas
while designing digital PCBs?
A. Width of signal lines
B. Distance between signal line and ground line
C. Signal Delays
D. Double Pulsing
a) A & B
b) B & C
c) C & D·
) A, B, C, D
15. What should be the resistance of 0.6 mm wide conductor with 15 cm length and 25 μm thickness of
standard copper foil? (Assume $\rho = 1.7241 \times 10^{-6} (at 20^{\circ} C)$
a) 118.2 m $\Omega$
b) $138.2 \text{ m}\Omega$
c) $172.4 \text{ m}\Omega$
d) 192.4 m $\Omega$
w) 13-11 mas
16. The actual cost of PCB can be evaluated on the basis of
a) PCB size & material
b) Number of layers
c) Vias on PCB
d) All of the above

12. Which terminology of PCB represents a thin photo-sensitive polymer by supporting photographic

pattern of single traces or IC pads for etching?

a) Prepregb) Etchingc) Photo-resist

- 17. Which factors contribute to the occurrence of mechanical stress?
- a) Resonance
- b) Cracked Solder Joints
- c) Both a and b
- d) None of the above
- 18. Which type of PCB requires minimum soldering on component side in order to avoid replacement oriented difficulties?
- a) Single-sided PCB
- b) Double-sided PCB
- c) Both a and b
- d) None of the above
- 19. What effects can be observed if the separate power and ground planes are provided with large conducting surfaces for better decoupling in PCB layouts?
- a) Increase in self-inductance
- b) Reduction in self-inductance
- c) Stability in self-inductance
- d) None of the above
- 20) What is the first step in PCB design
- a) Specification
- b) Schematic
- c) Manufacturing file
- d) Simulation

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# SSM Institute of Engineering and Technology

Dindigul – Palani Highway, Dindigul – 624 002

### CERTIFICATE

This is certified that Mr.N.KALAISELVAN, IV year - Electrical and Electronics Engineering department has successfully completed the Course on PCB DESIGN & FABRICATION on December 2019.